THE DATASHEET OF

PCA9554TS,118

www.win-source.net 0086-755-83957316

PCA9554; PCA9554A

8-bit I²C-bus and SMBus I/O port with interrupt

Rev. 10 — 8 November 2017 Product data sheet

1. General description

The PCA9554 and PCA9554A are 16-pin CMOS devices that provide 8 bits of General Purpose parallel Input/Output (GPIO) expansion for I²C-bus/SMBus applications and were developed to enhance the NXP Semiconductors family of I²C-bus I/O expanders. The improvements include higher drive capability, 5 V I/O tolerance, lower supply current, individual I/O configuration, 400 kHz clock frequency, and smaller packaging. I/O expanders provide a simple solution when additional I/O is needed for ACPI power switches, sensors, push buttons, LEDs, fans, and so on.

The PCA9554/PCA9554A consist of an 8-bit Configuration register (Input or Output selection); 8-bit Input Port register, 8-bit Output Port register and an 8-bit Polarity Inversion register (active HIGH or active LOW operation). The system master can enable the I/Os as either inputs or outputs by writing to the I/O configuration bits. The data for each input or output is kept in the corresponding Input Port or Output Port register. The polarity of the read register can be inverted with the Polarity Inversion register. All registers can be read by the system master. Although pin-to-pin and I²C-bus address compatible with the PCF8574 series, software changes are required due to the enhancements and are discussed in *Application Note AN469*.

The PCA9554/PCA9554A open-drain interrupt output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system master that an input state has changed. The power-on reset sets the registers to their default values and initializes the device state machine.

Three hardware pins (A0, A1, A2) vary the fixed I²C-bus address and allow up to eight devices to share the same I²C-bus/SMBus. The PCA9554A is identical to the PCA9554 except that the fixed I²C-bus address is different allowing up to sixteen of these devices (eight of each) on the same I²C-bus/SMBus.

2. Features and benefits

- Operating power supply voltage range of 2.3 V to 5.5 V
- 5 V tolerant I/Os
- Polarity Inversion register
- Active LOW interrupt output
- Low standby current
- Noise filter on SCL/SDA inputs
- No glitch on power-up
- Internal power-on reset
- 8 I/O pins which default to 8 inputs
- 0 Hz to 400 kHz clock frequency

- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101
- Latch-up testing is done to JEDEC Standard JESD78 which exceeds 100 mA
- AEC-Q100 compliance available
- Packages offered: SO16, SSOP16, SSOP20, TSSOP16, HVQFN16 (2 versions: 4 × 4 × 0.85 mm and 3 × 3 × 0.85 mm), and bare die

3. Ordering information

Table 1. Ordering information

Type number	Topside marking	Package		
		Name	Description	Version
PCA9554D	PCA9554D	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1
PCA9554AD	PCA9554AD			
PCA9554DB	9554DB	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
PCA9554ADB	9554A			
PCA9554TS	PCA9554	SSOP20	plastic shrink small outline package; 20 leads; body width 4.4 mm	SOT266-1
PCA9554ATS	PA9554A			
PCA9554PW	9554DH	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
PCA9554PW/Q900[1]	9554DH			
PCA9554APW	9554ADH			
PCA9554BS	9554	HVQFN16	plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 × 4 × 0.85 mm	SOT629-1
PCA9554ABS	554A			
PCA9554BS3	P54	HVQFN16	plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 × 3 × 0.85 mm	SOT758-1
PCA9554ABS3	54A			
PCA9554U	-	bare die	-	-

[1] PCA9554PW/Q900 is AEC-Q100 compliant. Contact **i2c.support@nxp.com** for PPAP.

3.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
PCA9554D	PCA9554D,112	SO16	Standard marking * IC's tube - DSC bulk pack	1920	T_{amb} = –40 °C to +85 °C
	PCA9554D,118	SO16	Reel 13" Q1/T1 *standard mark SMD	1000	T_{amb} = –40 °C to +85 °C
PCA9554AD	PCA9554AD,112	SO16	Standard marking * IC's tube - DSC bulk pack	1920	T_{amb} = –40 °C to +85 °C
	PCA9554AD,118	SO16	Reel 13" Q1/T1 *standard mark SMD	1000	T_{amb} = –40 °C to +85 °C
PCA9554DB	PCA9554DB,112	SSOP16	Standard marking * IC's tube - DSC bulk pack	1092	T_{amb} = –40 °C to +85 °C
	PCA9554DB,118	SSOP16	Reel 13" Q1/T1 *standard mark SMD	2000	T_{amb} = –40 °C to +85 °C

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Table 2. Ordering options *…continued*

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature
PCA9554ADB	PCA9554ADB,112	SSOP16	Standard marking * IC's tube - DSC bulk pack	1092	T_{amb} = –40 °C to +85 °C
	PCA9554ADB,118	SSOP16	Reel 13" Q1/T1 *standard mark SMD	2000	T_{amb} = –40 °C to +85 °C
PCA9554TS	PCA9554TS,112	SSOP20	Standard marking * IC's tube - DSC bulk pack	1350	T_{amb} = –40 °C to +85 °C
	PCA9554TS,118	SSOP20	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = –40 °C to +85 °C
PCA9554ATS	PCA9554ATS,112	SSOP20	Standard marking * IC's tube - DSC bulk pack	1350	T_{amb} = –40 °C to +85 °C
	PCA9554ATS,118	SSOP20	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = –40 °C to +85 °C
PCA9554PW	PCA9554PW,112	TSSOP16	Standard marking * IC's tube - DSC bulk pack	2400	T_{amb} = –40 °C to +85 °C
	PCA9554PW,118	TSSOP16	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = –40 °C to +85 °C
PCA9554PW/Q900	PCA9554PW/Q900,118	TSSOP16	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = –40 °C to +85 °C
PCA9554APW	PCA9554APW,112	TSSOP16	Standard marking * IC's tube - DSC bulk pack	2400	T_{amb} = –40 °C to +85 °C
	PCA9554APW,118	TSSOP16	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = –40 °C to +85 °C
PCA9554BS	PCA9554BS,118	HVQFN16	Reel 13" Q1/T1 *standard mark SMD	6000	T_{amb} = –40 °C to +85 °C
PCA9554ABS	PCA9554ABS,118	HVQFN16	Reel 13" Q1/T1 *standard mark SMD	6000	T_{amb} = –40 °C to +85 °C
PCA9554BS3	PCA9554BS3,118	HVQFN16	Reel 13" Q1/T1 *standard mark SMD	6000	T_{amb} = –40 °C to +85 °C
PCA9554ABS3	PCA9554ABS3,118	HVQFN16	Reel 13" Q1/T1 *standard mark SMD	6000	T_{amb} = –40 °C to +85 °C
PCA9554U	PCA9554U,029	bare die	Reel 7" Q1/T1 *no mark die mounted on punched tape	7000	T_{amb} = –40 °C to +85 °C

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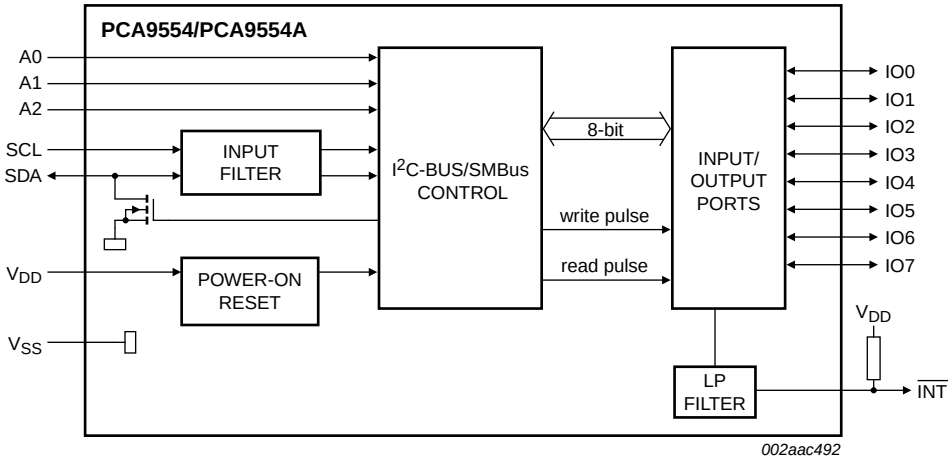
4. Block diagram



All I/Os are set to inputs at reset.

Fig 1. Block diagram of PCA9554/PCA9554A

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5. Pinning information

5.1 Pinning

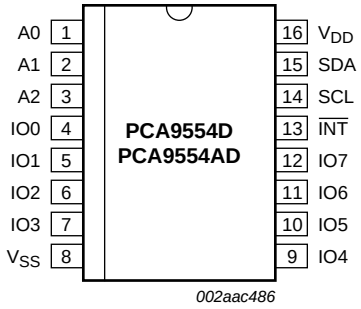


Fig 2. Pin configuration for SO16

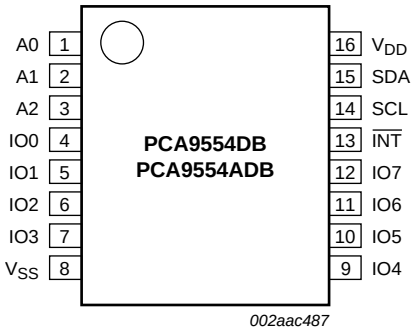


Fig 3. Pin configuration for SSOP16

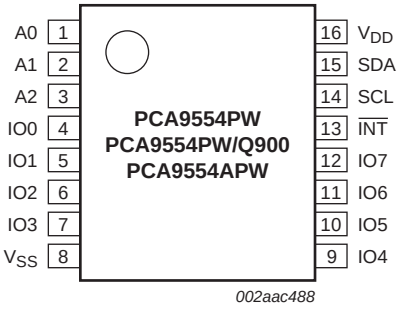


Fig 4. Pin configuration for TSSOP16

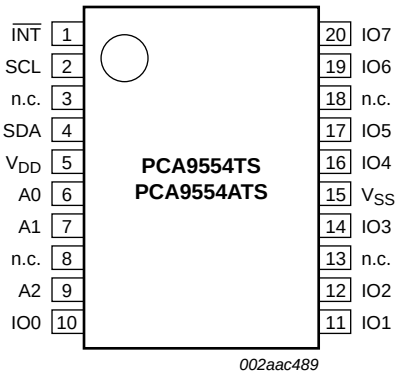
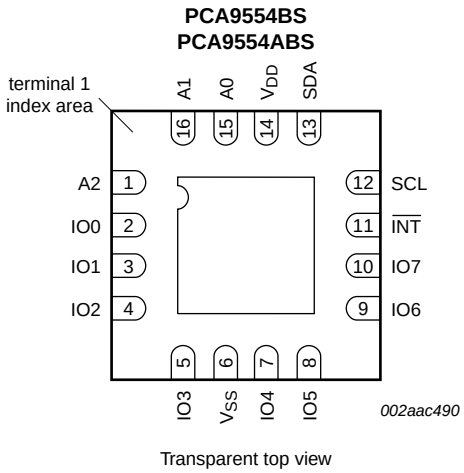
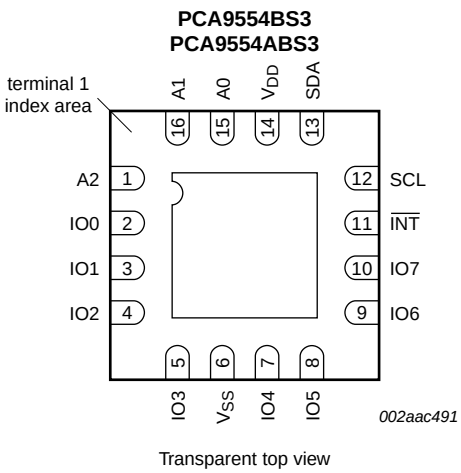


Fig 5. Pin configuration for SSOP20



Transparent top view

Fig 6. Pin configuration for HVQFN16 (SOT629-1)



Transparent top view

Fig 7. Pin configuration for HVQFN16 (SOT758-1)

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5.2 Pin description

Table 3. Pin description

Symbol	Pin			Description
	SO16, SSOP16, TSSOP16	HVQFN16	SSOP20	
A0	1	15	6	address input 0
A1	2	16	7	address input 1
A2	3	1	9	address input 2
IO0	4	2	10	input/output 0
IO1	5	3	11	input/output 1
IO2	6	4	12	input/output 2
IO3	7	5	14	input/output 3
V_{SS}	8	6[1]	15	supply ground
IO4	9	7	16	input/output 4
IO5	10	8	17	input/output 5
IO6	11	9	19	input/output 6
IO7	12	10	20	input/output 7
$\overline{INT}$	13	11	1	interrupt output (open-drain)
SCL	14	12	2	serial clock line
SDA	15	13	4	serial data line
V_{DD}	16	14	5	supply voltage
n.c.	-	-	3, 8, 13, 18	not connected

[1] HVQFN16 package die supply ground is connected to both V_{SS} pin and exposed center pad. V_{SS} pin must be connected to supply ground for proper device operation. For enhanced thermal, electrical, and board level performance, the exposed pad needs to be soldered to the board using a corresponding thermal pad on the board and for proper heat conduction through the board, thermal vias need to be incorporated in the PCB in the thermal pad region.

6. Functional description

Refer to Figure 1 “Block diagram of PCA9554/PCA9554A”.

6.1 Registers

6.1.1 Command byte

Table 4. Command byte

Command	Protocol	Function
0	read byte	Input Port register
1	read/write byte	Output Port register
2	read/write byte	Polarity Inversion register
3	read/write byte	Configuration register

The command byte is the first byte to follow the address byte during a write transmission. It is used as a pointer to determine which of the following registers will be written or read.

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6.1.2 Register 0 - Input Port register

This register is a read-only port. It reflects the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by Register 3. Writes to this register have no effect.

The default 'X' is determined by the externally applied logic level, normally '1' when no external signal externally applied because of the internal pull-up resistors.

Table 5. Register 0 - Input Port register bit description

Bit	Symbol	Access	Value	Description
7	I7	read only	X	determined by externally applied logic level
6	I6	read only	X	
5	I5	read only	X	
4	I4	read only	X	
3	I3	read only	X	
2	I2	read only	X	
1	I1	read only	X	
0	I0	read only	X	

6.1.3 Register 1 - Output Port register

This register reflects the outgoing logic levels of the pins defined as outputs by Register 3. Bit values in this register have no effect on pins defined as inputs. Reads from this register return the value that is in the flip-flop controlling the output selection, **not** the actual pin value.

Table 6. Register 1 - Output Port register bit description

*Legend: * default value.*

Bit	Symbol	Access	Value	Description
7	O7	R	1*	reflects outgoing logic levels of pins defined as outputs by Register 3
6	O6	R	1*	
5	O5	R	1*	
4	O4	R	1*	
3	O3	R	1*	
2	O2	R	1*	
1	O1	R	1*	
0	O0	R	1*	

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6.1.4 Register 2 - Polarity Inversion register

This register allows the user to invert the polarity of the Input Port register data. If a bit in this register is set (written with '1'), the corresponding Input Port data is inverted. If a bit in this register is cleared (written with a '0'), the Input Port data polarity is retained.

Table 7. Register 2 - Polarity Inversion register bit description

*Legend: * default value.*

Bit	Symbol	Access	Value	Description
7	N7	R/W	0*	inverts polarity of Input Port register data 0 = Input Port register data retained (default value) 1 = Input Port register data inverted
6	N6	R/W	0*	
5	N5	R/W	0*	
4	N4	R/W	0*	
3	N3	R/W	0*	
2	N2	R/W	0*	
1	N1	R/W	0*	
0	N0	R/W	0*	

6.1.5 Register 3 - Configuration register

This register configures the directions of the I/O pins. If a bit in this register is set, the corresponding port pin is enabled as an input with high-impedance output driver. If a bit in this register is cleared, the corresponding port pin is enabled as an output. At reset, the I/Os are configured as inputs with a weak pull-up to V_{DD}.

Table 8. Register 3 - Configuration register bit description

*Legend: * default value.*

Bit	Symbol	Access	Value	Description
7	C7	R/W	1*	configures the directions of the I/O pins 0 = corresponding port pin enabled as an output 1 = corresponding port pin configured as input (default value)
6	C6	R/W	1*	
5	C5	R/W	1*	
4	C4	R/W	1*	
3	C3	R/W	1*	
2	C2	R/W	1*	
1	C1	R/W	1*	
0	C0	R/W	1*	

6.2 Power-on reset

When power is applied to V_{DD}, an internal Power-On Reset (POR) holds the PCA9554/PCA9554A in a reset condition until V_{DD} has reached V_{POR}. At that point, the reset condition is released and the PCA9554/PCA9554A registers and state machine will initialize to their default states. Thereafter, V_{DD} must be lowered below 0.2 V to reset the device.

For a power reset cycle, V_{DD} must be lowered below 0.2 V and then restored to the operating voltage.

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6.3 Interrupt output

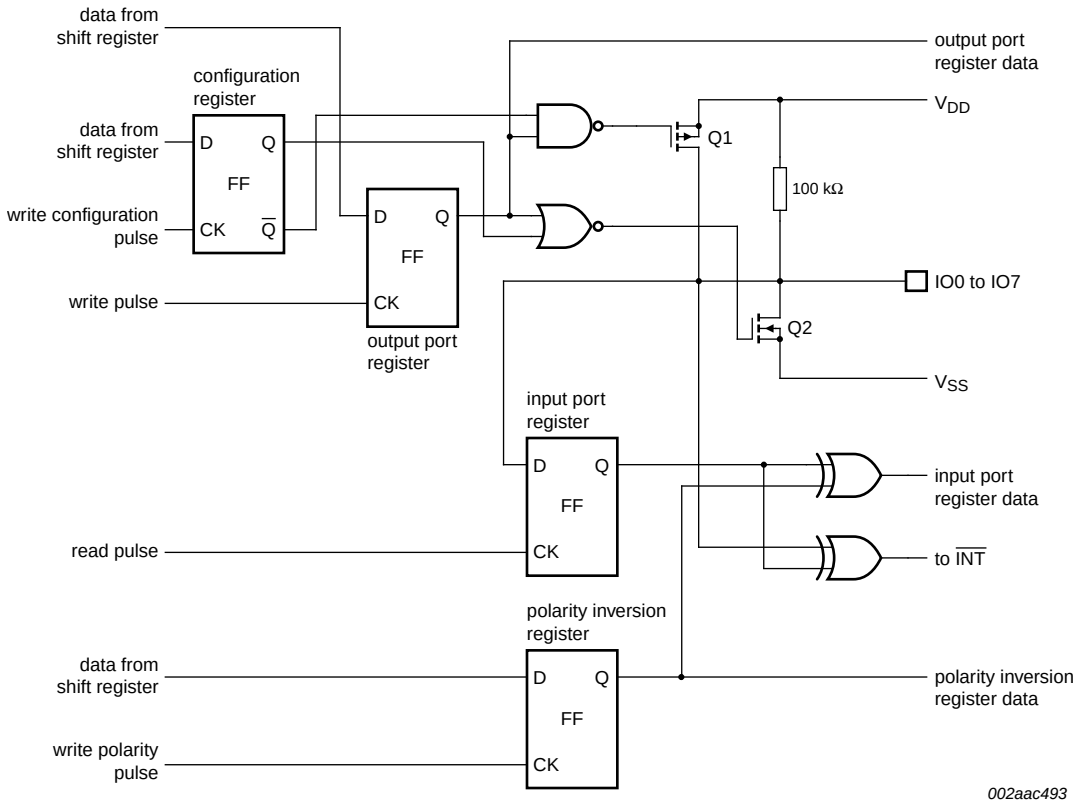
The open-drain interrupt output is activated when one of the port pins change state and the pin is configured as an input. The interrupt is deactivated when the input returns to its previous state or the Input Port register is read.

Note that changing an I/O from and output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register.

6.4 I/O port

When an I/O is configured as an input, FETs Q1 and Q2 are off, creating a high-impedance input with a weak pull-up (100 kΩ typ.) to V_{DD}. The input voltage may be raised above V_{DD} to a maximum of 5.5 V.

If the I/O is configured as an output, then either Q1 or Q2 is enabled, depending on the state of the Output Port register. Care should be exercised if an external voltage is applied to an I/O configured as an output because of the low-impedance paths that exist between the pin and either V_{DD} or V_{SS}.



Remark: At power-on reset, all registers return to default values.

Fig 8. Simplified schematic of IO0 to IO7

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6.5 Device address

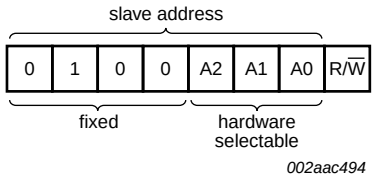

Fig 9. PCA9554 device address

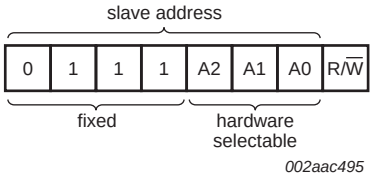

Fig 10. PCA9554A device address

6.6 Bus transactions

Data is transmitted to the PCA9554/PCA9554A registers using the Write mode as shown in Figure 11 and Figure 12. Data is read from the PCA9554/PCA9554A registers using the Read mode as shown in Figure 13 and Figure 14. These devices do not implement an auto-increment function, so once a command byte has been sent, the register which was addressed will continue to be accessed by reads until a new command byte has been sent.

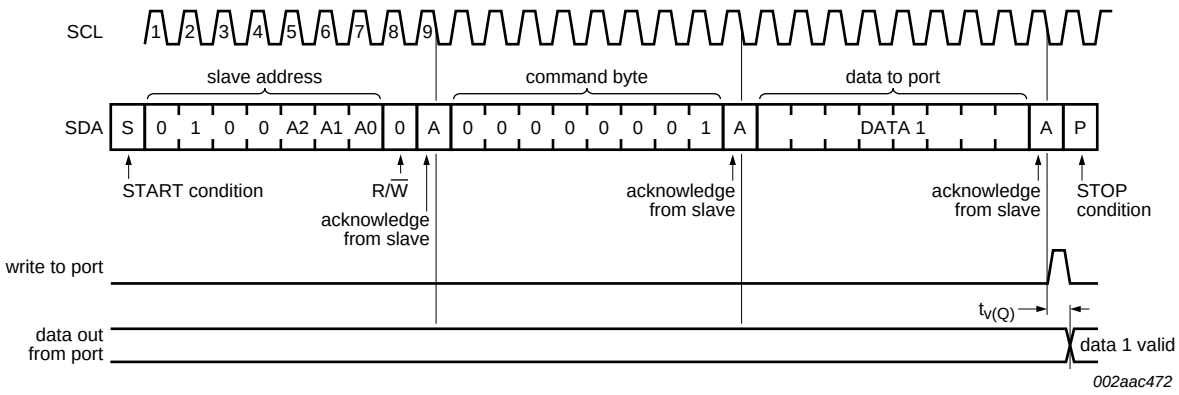

Fig 11. Write to Output Port register

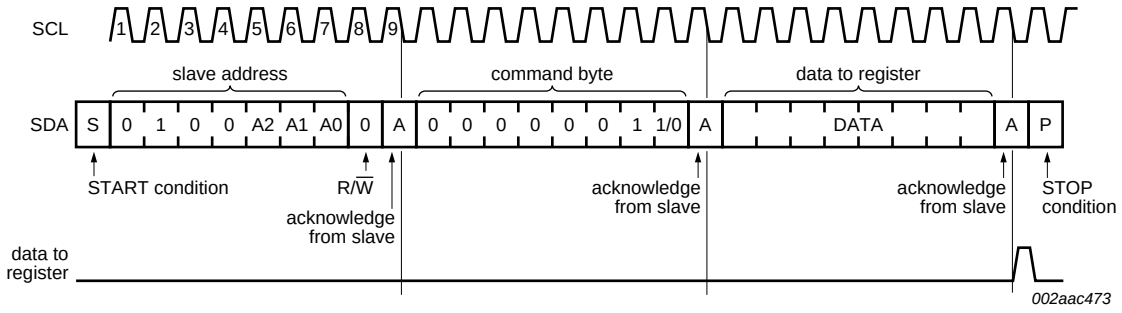

Fig 12. Write to Configuration register or Polarity Inversion register

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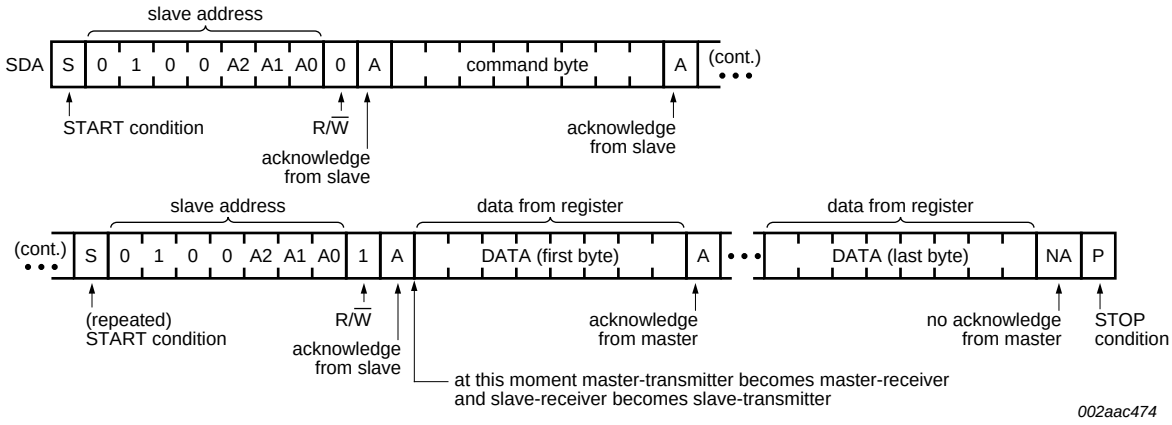
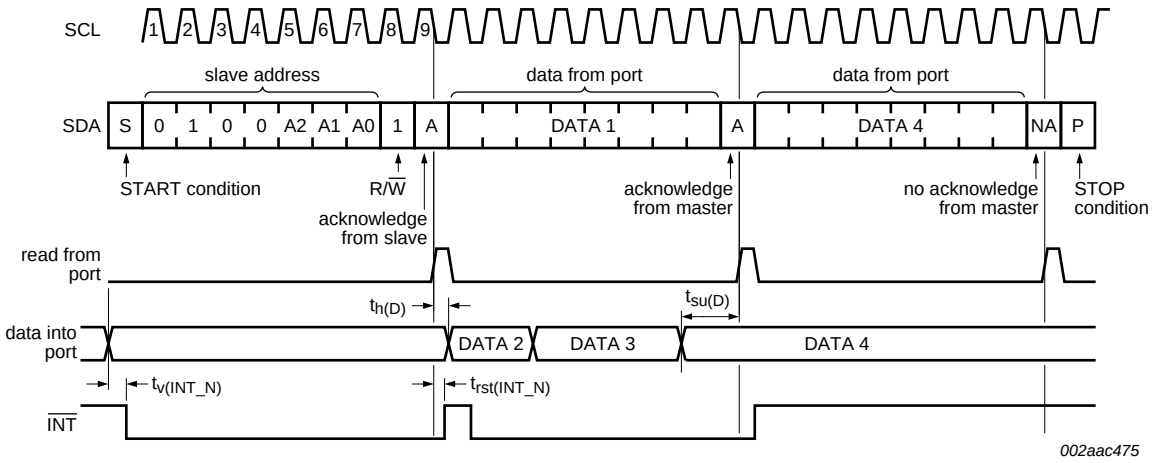


Fig 13. Read from register



This figure assumes the command byte has previously been programmed with 00h.

Transfer of data can be stopped at any moment by a STOP condition.

Fig 14. Read Input Port register

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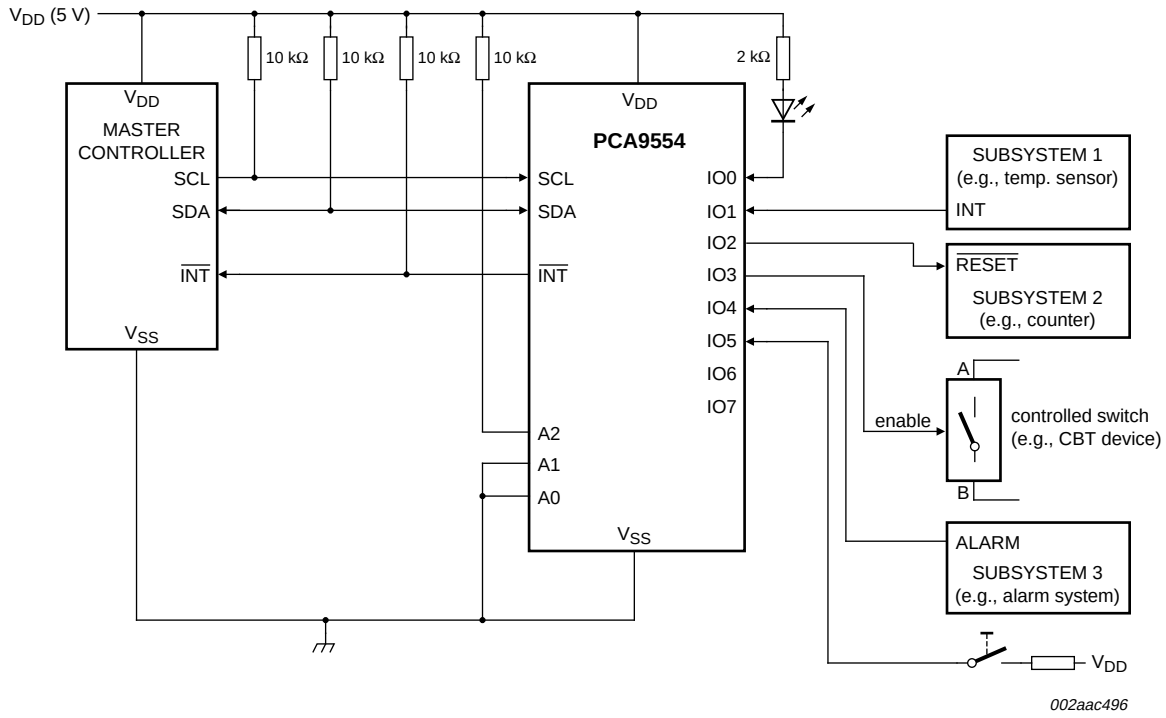
7. Application design-in information



Device address configured as 0100 100X for this example.

IO0, IO1, IO2 configured as outputs.

IO3, IO4, IO5 configured as inputs.

IO6 and IO7 are not used and must be configured as outputs.

Fig 15. Typical application

8. Limiting values

Table 9. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage			–0.5	+6.0	V
I_I	input current			-	±20	mA
$V_{I/O}$	voltage on an input/output pin			V_{SS} – 0.5	5.5	V
$I_{O(IOn)}$	output current on pin IOn			-	±50	mA
I_{DD}	supply current			-	85	mA
I_{SS}	ground supply current			-	100	mA
P_{tot}	total power dissipation			-	200	mW
T_{stg}	storage temperature			–65	+150	°C
T_{amb}	ambient temperature	operating		–40	+85	°C

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9. Static characteristics

Table 10. Static characteristics

V_{DD} = 2.3 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Supplies							
V_{DD}	supply voltage			2.3	-	5.5	V
I_{DD}	supply current	operating mode; V_{DD} = 5.5 V; no load; f_{SCL} = 100 kHz		-	104	175	µA
I_{stb}	standby current	Standby mode; V_{DD} = 5.5 V; no load; $V_I = V_{SS}$; f_{SCL} = 0 kHz; I/O = inputs		-	550	700	µA
		Standby mode; V_{DD} = 5.5 V; no load; $V_I = V_{DD}$; f_{SCL} = 0 kHz; I/O = inputs		-	0.25	1	µA
V_{POR}	power-on reset voltage	no load; $V_I = V_{DD}$ or V_{SS}	[1]	-	1.7	2.2	V
Input SCL; input/output SDA							
V_{IL}	LOW-level input voltage			−0.5	-	$+0.3V_{DD}$	V
V_{IH}	HIGH-level input voltage			$0.7V_{DD}$	-	5.5	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V		3	6	-	mA
I_L	leakage current	$V_I = V_{DD} = V_{SS}$		−1	-	+1	µA
C_i	input capacitance	$V_I = V_{SS}$		-	6	10	pF
I/Os							
V_{IL}	LOW-level input voltage			−0.5	-	+0.8	V
V_{IH}	HIGH-level input voltage			2.0	-	5.5	V
I_{OL}	LOW-level output current	V_{OL} = 0.5 V; V_{DD} = 2.3 V	[2]	8	10	-	mA
		V_{OL} = 0.7 V; V_{DD} = 2.3 V	[2]	10	13	-	mA
		V_{OL} = 0.5 V; V_{DD} = 3.0 V	[2]	8	14	-	mA
		V_{OL} = 0.7 V; V_{DD} = 3.0 V	[2]	10	19	-	mA
		V_{OL} = 0.5 V; V_{DD} = 4.5 V	[2]	8	17	-	mA
		V_{OL} = 0.7 V; V_{DD} = 4.5 V	[2]	10	24	-	mA
V_{OH}	HIGH-level output voltage	I_{OH} = −8 mA; V_{DD} = 2.3 V	[3]	1.8	-	-	V
		I_{OH} = −10 mA; V_{DD} = 2.3 V	[3]	1.7	-	-	V
		I_{OH} = −8 mA; V_{DD} = 3.0 V	[3]	2.6	-	-	V
		I_{OH} = −10 mA; V_{DD} = 3.0 V	[3]	2.5	-	-	V
		I_{OH} = −8 mA; V_{DD} = 4.75 V	[3]	4.1	-	-	V
		I_{OH} = −10 mA; V_{DD} = 4.75 V	[3]	4.0	-	-	V
I_{LI}	input leakage current	V_{DD} = 3.6 V; $V_I = V_{DD}$		−1	-	+1	µA
I_L	leakage current	V_{DD} = 5.5 V; $V_I = V_{SS}$		-	-	−100	µA
C_i	input capacitance			-	3.7	5	pF
C_o	output capacitance			-	3.7	5	pF
Interrupt INT							
I_{OL}	LOW-level output current	V_{OL} = 0.4 V		3	-	-	mA

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Table 10. Static characteristics *…continued*

V_{DD} = 2.3 V to 5.5 V; V_{SS} = 0 V; T_{amb} = −40 °C to +85 °C; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Select inputs A0, A1, A2							
V_{IL}	LOW-level input voltage			−0.5	-	0.8	V
V_{IH}	HIGH-level input voltage			2.0	-	5.5	V
I_{LI}	input leakage current			−1	-	1	µA

[1] V_{DD} must be lowered to 0.2 V for at least 5 µs in order to reset part.

[2] Each I/O must be externally limited to a maximum of 25 mA and the device must be limited to a maximum current of 100 mA.

[3] The total current sourced by all I/Os must be limited to 85 mA.

10. Dynamic characteristics

Table 11. Dynamic characteristics

Symbol	Parameter	Conditions		Standard-mode I²C-bus		Fast-mode I²C-bus		Unit
				Min	Max	Min	Max	
f_{SCL}	SCL clock frequency			0	100	0	400	kHz
t_{BUF}	bus free time between a STOP and START condition			4.7	-	1.3	-	µs
$t_{HD;STA}$	hold time (repeated) START condition			4.0	-	0.6	-	µs
$t_{SU;STA}$	set-up time for a repeated START condition			4.7	-	0.6	-	µs
$t_{SU;STO}$	set-up time for STOP condition			4.0	-	0.6	-	µs
$t_{HD;DAT}$	data hold time			0	-	0	-	µs
$t_{VD;ACK}$	data valid acknowledge time		[1]	0.3	3.45	0.1	0.9	µs
$t_{VD;DAT}$	data valid time		[2]	300	-	50	-	ns
$t_{SU;DAT}$	data set-up time			250	-	100	-	ns
t_{LOW}	LOW period of the SCL clock			4.7	-	1.3	-	µs
t_{HIGH}	HIGH period of the SCL clock			4.0	-	0.6	-	µs
t_r	rise time of both SDA and SCL signals			-	1000	$20 + 0.1C_b$ [3]	300	ns
t_f	fall time of both SDA and SCL signals			-	300	$20 + 0.1C_b$ [3]	300	ns
t_{SP}	pulse width of spikes that must be suppressed by the input filter			-	50	-	50	ns
Port timing								
$t_{v(Q)}$	data output valid time			-	200	-	200	ns
$t_{su(D)}$	data input set-up time			100	-	100	-	ns
$t_{h(D)}$	data input hold time			1	-	1	-	µs
Interrupt timing								
$t_{v(INT_N)}$	valid time on pin $\overline{INT}$			-	4	-	4	µs
$t_{rst(INT_N)}$	reset time on pin $\overline{INT}$			-	4	-	4	µs

[1] $t_{VD;ACK}$ = time for Acknowledgement signal from SCL LOW to SDA (out) LOW.

[2] $t_{VD;DAT}$ = minimum time for SDA data output to be valid following SCL LOW.

[3] C_b = total capacitance of one bus line in pF.

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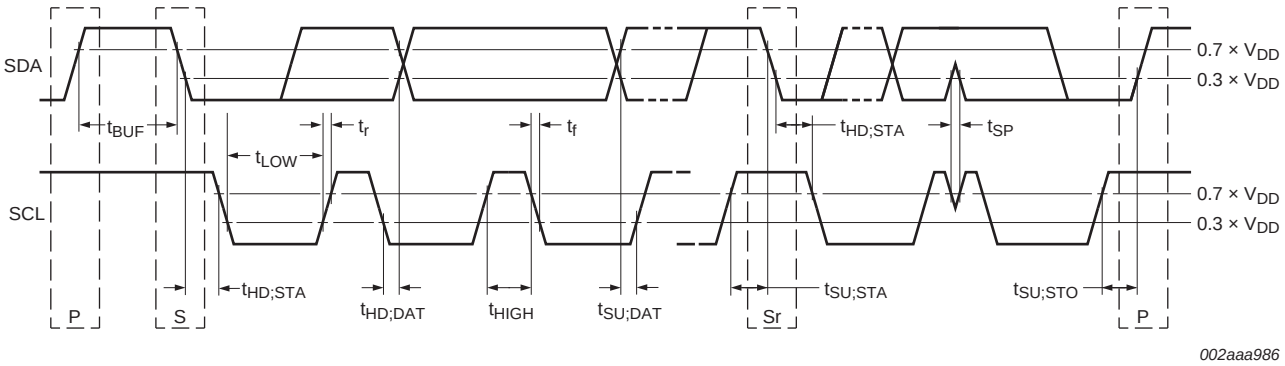

Fig 16. Definition of timing

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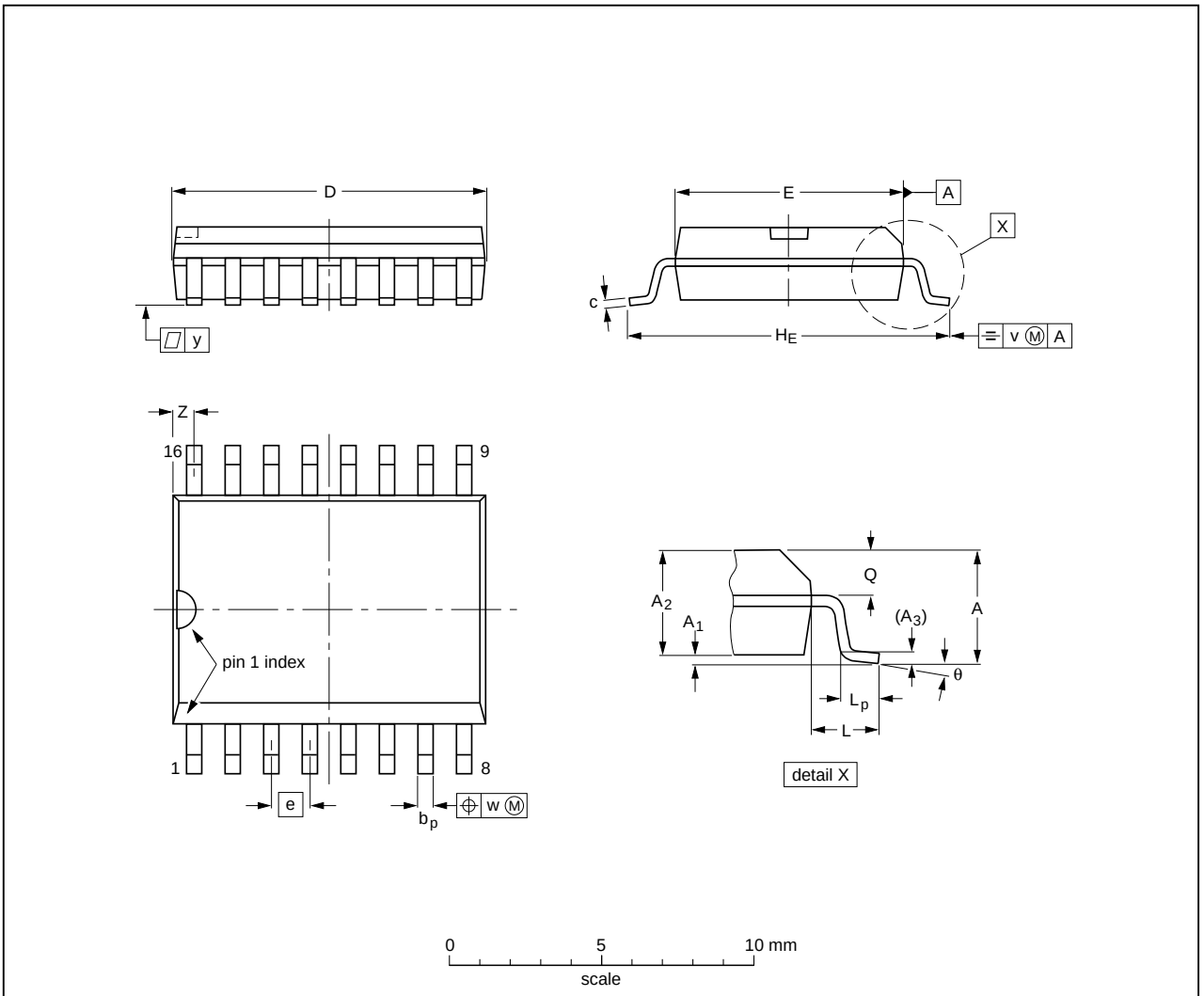
11. Package outline

SO16: plastic small outline package; 16 leads; body width 7.5 mm **SOT162-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT162-1	075E03	MS-013				~~99-12-27~~ 03-02-19

Fig 17. Package outline SOT162-1 (SO16)

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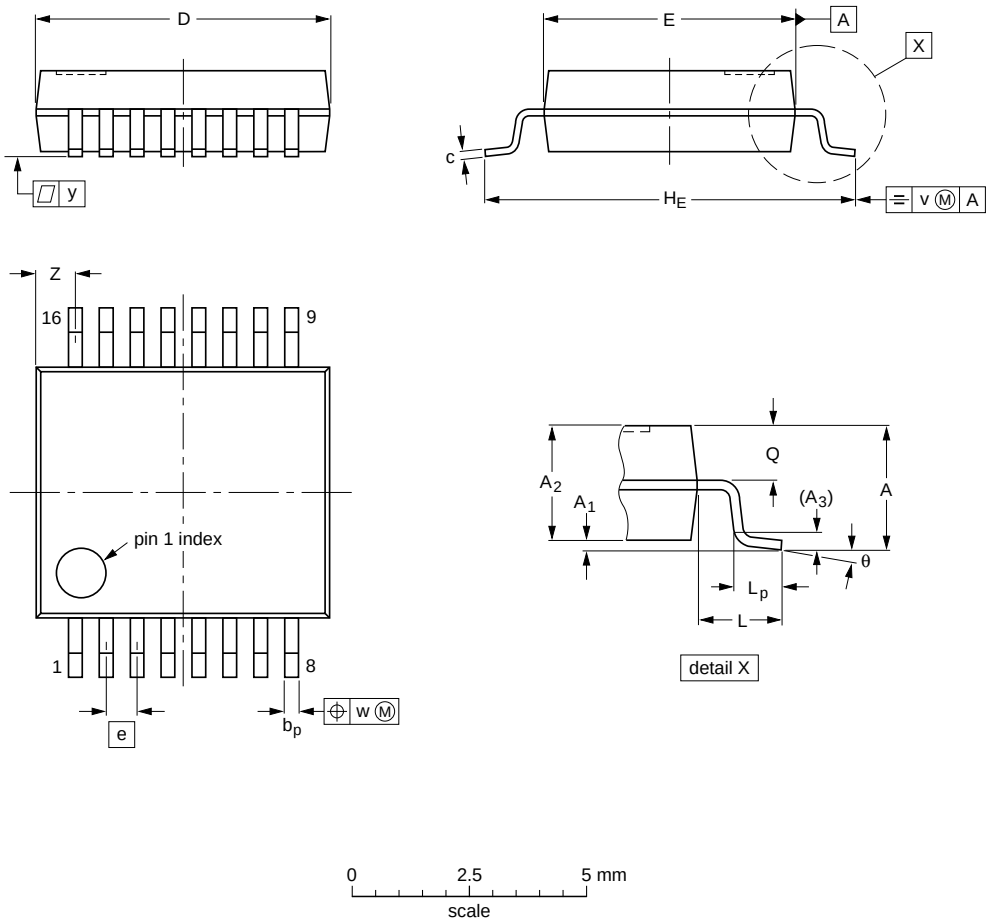
SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm **SOT338-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	6.4 6.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	1.00 0.55	8^o 0^o

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT338-1		MO-150				~~99-12-27~~ 03-02-19

Fig 18. Package outline SOT338-1 (SSOP16)

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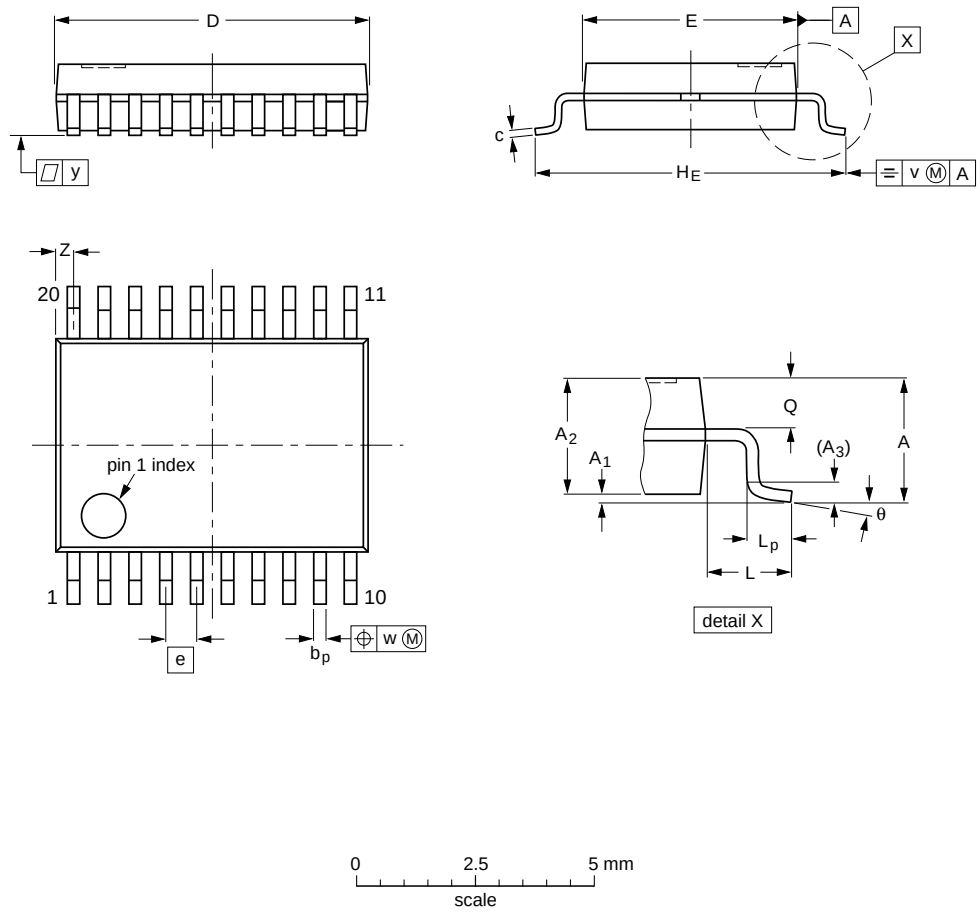
SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm **SOT266-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.5	0.15 0	1.4 1.2	0.25	0.32 0.20	0.20 0.13	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.45	0.65 0.45	0.2	0.13	0.1	0.48 0.18	10^o 0^o

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT266-1		MO-152				~~99-12-27~~ 03-02-19

Fig 19. Package outline SOT266-1 (SSOP20)

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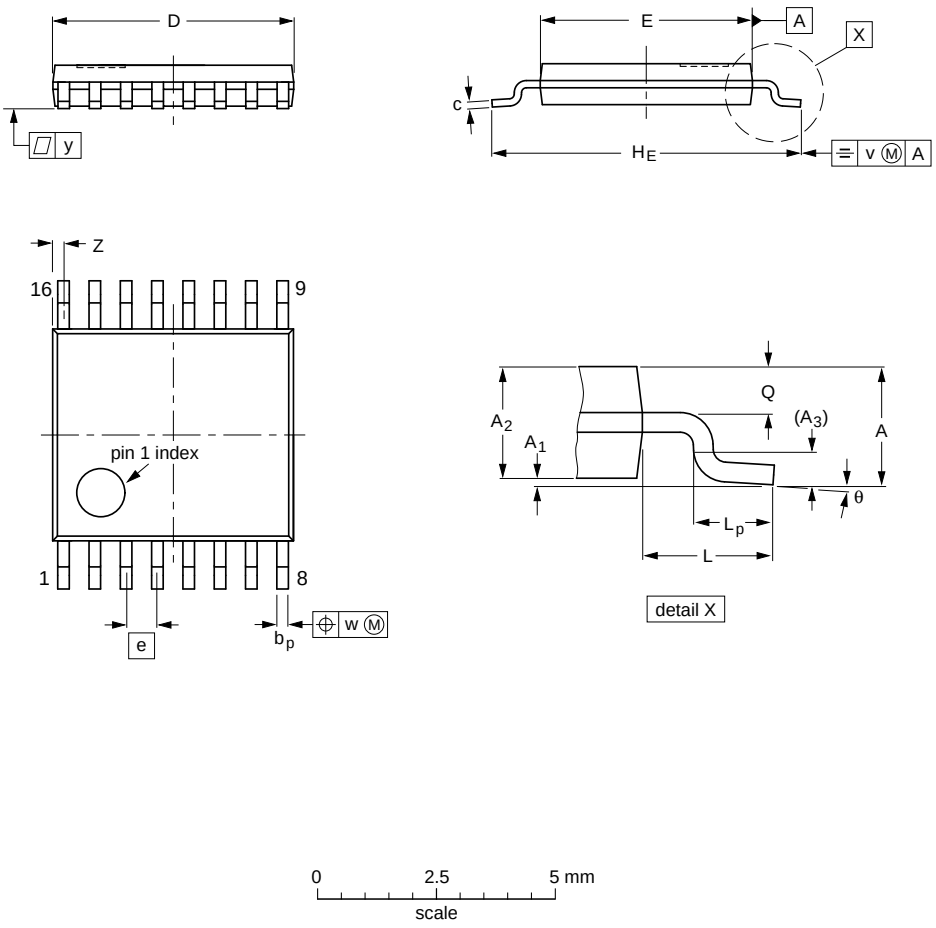
TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig 20. Package outline SOT403-1 (TSSOP16)

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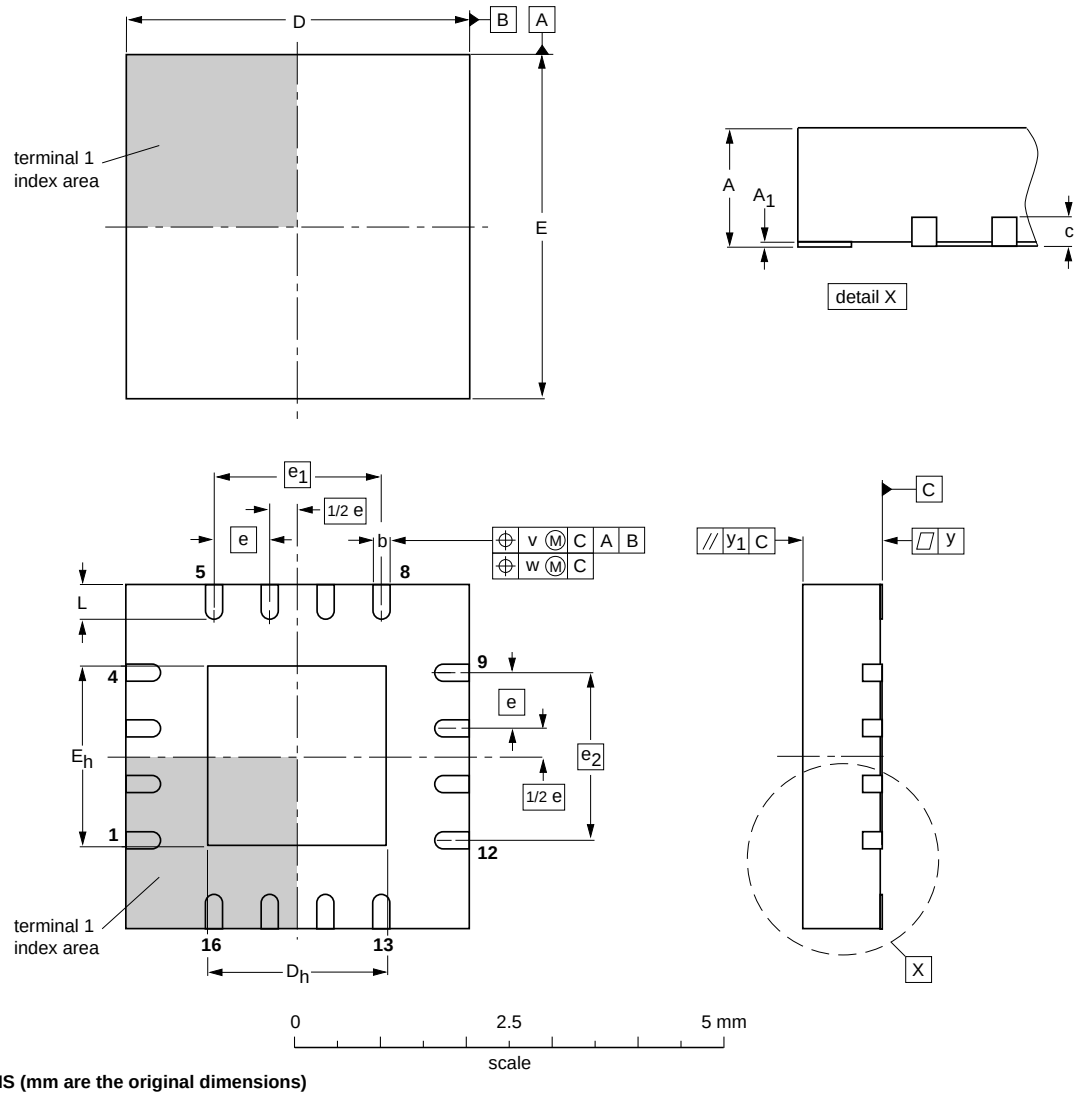
HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 4 x 4 x 0.85 mm **SOT629-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A1	b	c	D(1)	Dh	E(1)	Eh	e	e1	e2	L	v	w	y	y1
mm	1	0.05 0.00	0.38 0.23	0.2	4.1 3.9	2.25 1.95	4.1 3.9	2.25 1.95	0.65	1.95	1.95	0.75 0.50	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT629-1	- - -	MO-220	- - -			~~01-08-08~~ 02-10-22

Fig 21. Package outline SOT629-1 (HVQFN16)

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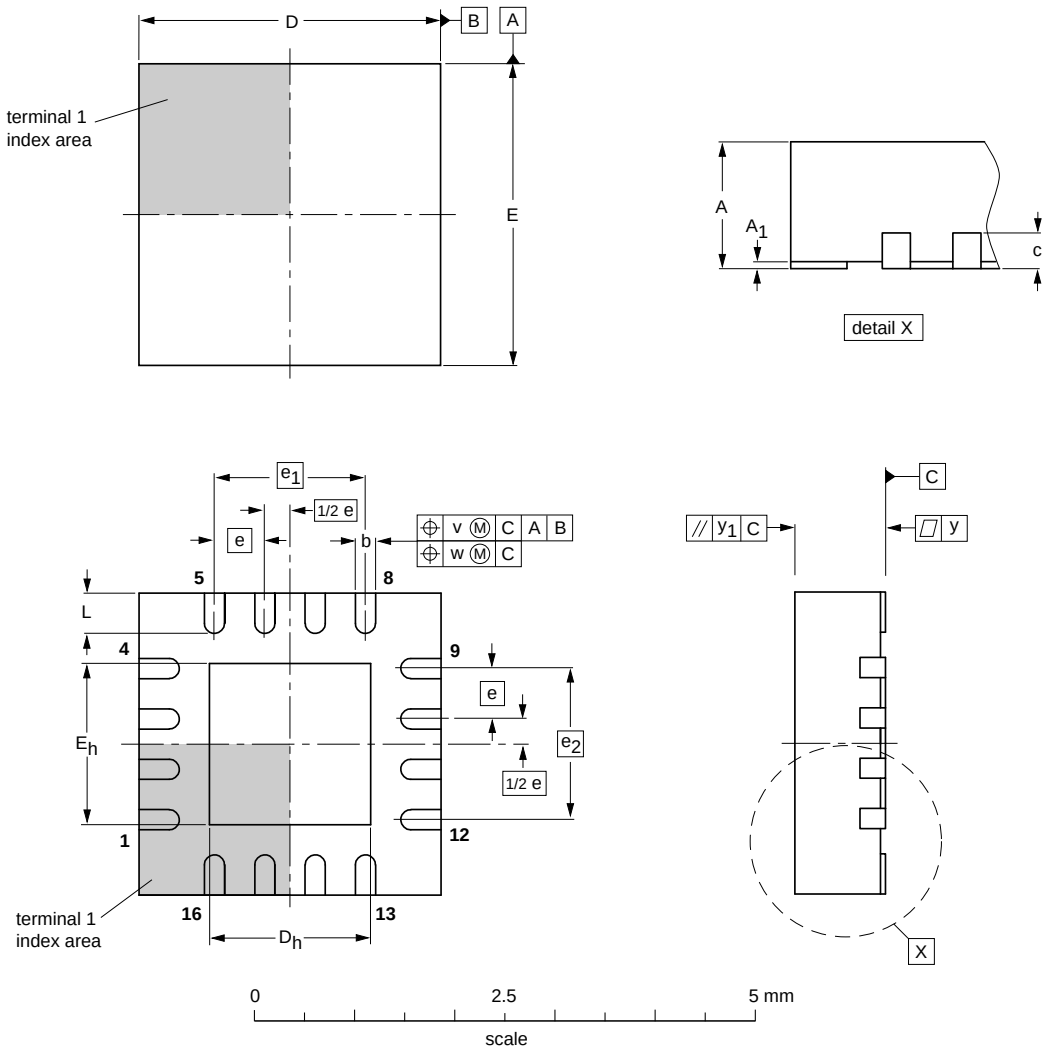
HVQFN16: plastic thermal enhanced very thin quad flat package; no leads; 16 terminals; body 3 x 3 x 0.85 mm **SOT758-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A(1) max.	A_1	b	c	D(1)	D_h	E(1)	E_h	e	e_1	e_2	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	1.75 1.45	3.1 2.9	1.75 1.45	0.5	1.5	1.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT758-1	- - -	MO-220	- - -			~~02-03-25~~ 02-10-21

Fig 22. Package outline SOT758-1 (HVQFN16)

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12. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

13. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

13.3 Wave soldering

Key characteristics in wave soldering are:

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- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 23) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 12 and 13

Table 12. SnPb eutectic process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 13. Lead-free process (from J-STD-020C)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 23.

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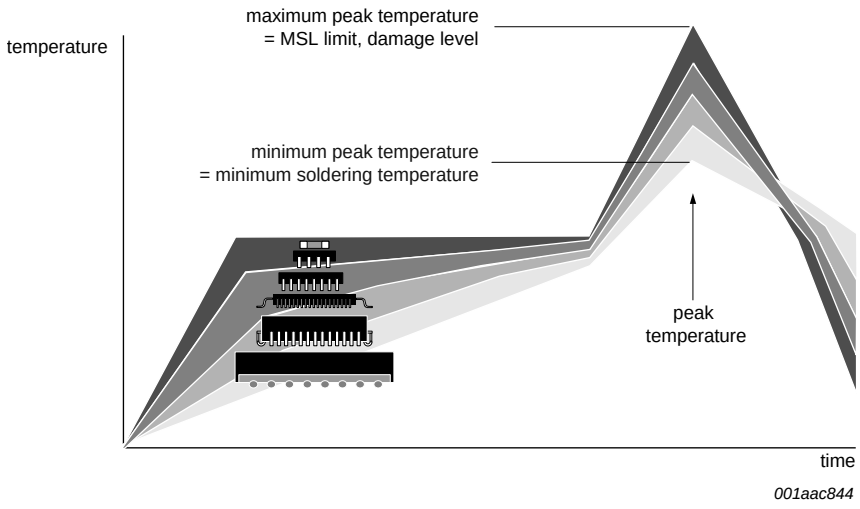

MSL: Moisture Sensitivity Level

Fig 23. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

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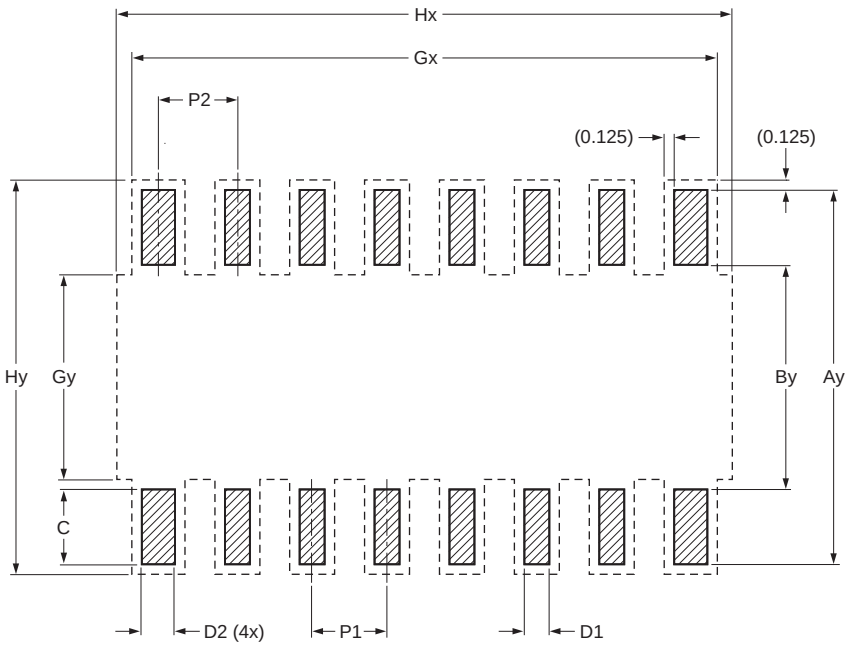
14. Soldering: PCB footprints

Footprint information for reflow soldering of SO16 package **SOT162-1**



Generic footprint pattern
Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
1.270	1.320	11.200	6.400	2.400	0.700	0.800	10.040	8.600	11.900	11.450

sot162-1_fr

Fig 24. PCB footprint for SOT162-1 (SO16); reflow soldering

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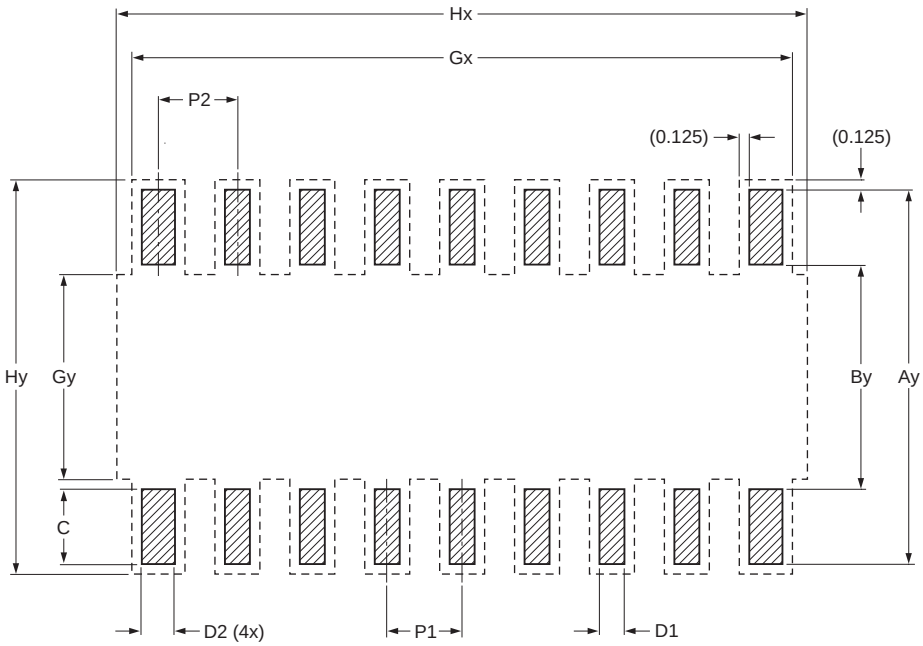
Footprint information for reflow soldering of SSOP16 package **SOT338-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.65	0.75	8.6	5.4	1.6	0.4	0.6	5.6	6.1	7.0	8.85

Issue date ~~09-02-22~~ 15-03-26

sot338-1_fr

Fig 25. PCB footprint for SOT338-1 (HVQFN16); reflow soldering

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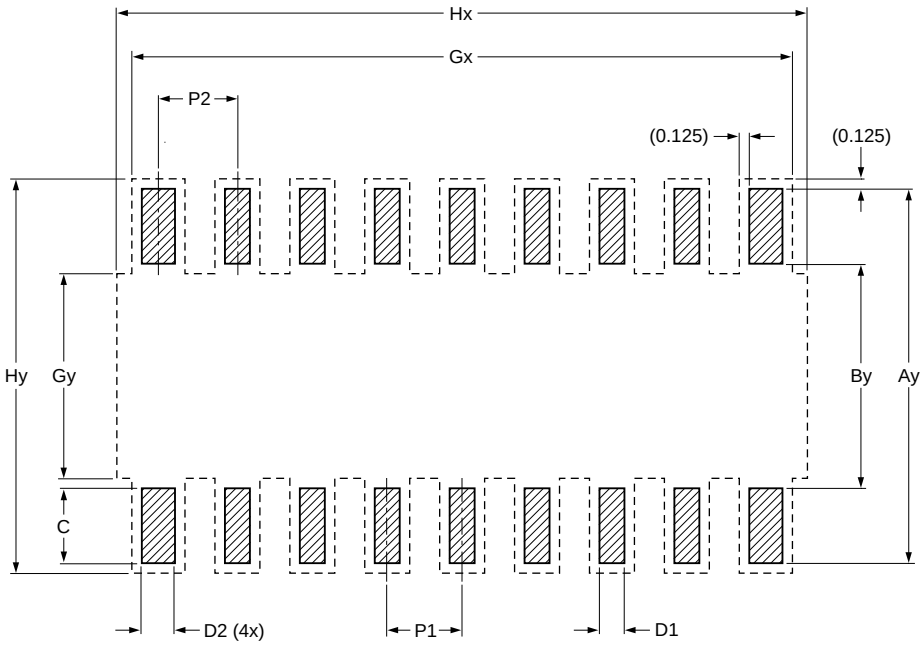
Footprint information for reflow soldering of SSOP20 package **SOT266-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	6.900	5.300	7.300	7.450

sot266-1_fr

Fig 26. PCB footprint for SOT266-1 (SSOP20); reflow soldering

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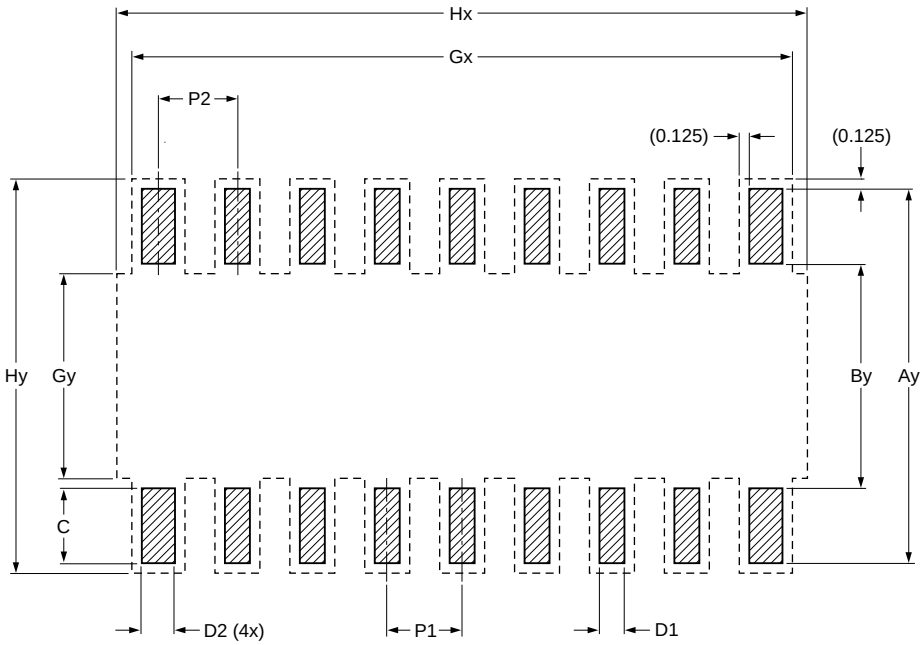
Footprint information for reflow soldering of TSSOP16 package **SOT403-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	5.600	5.300	5.800	7.450

sot403-1_fr

Fig 27. PCB footprint for SOT403-1 (TSSOP16); reflow soldering

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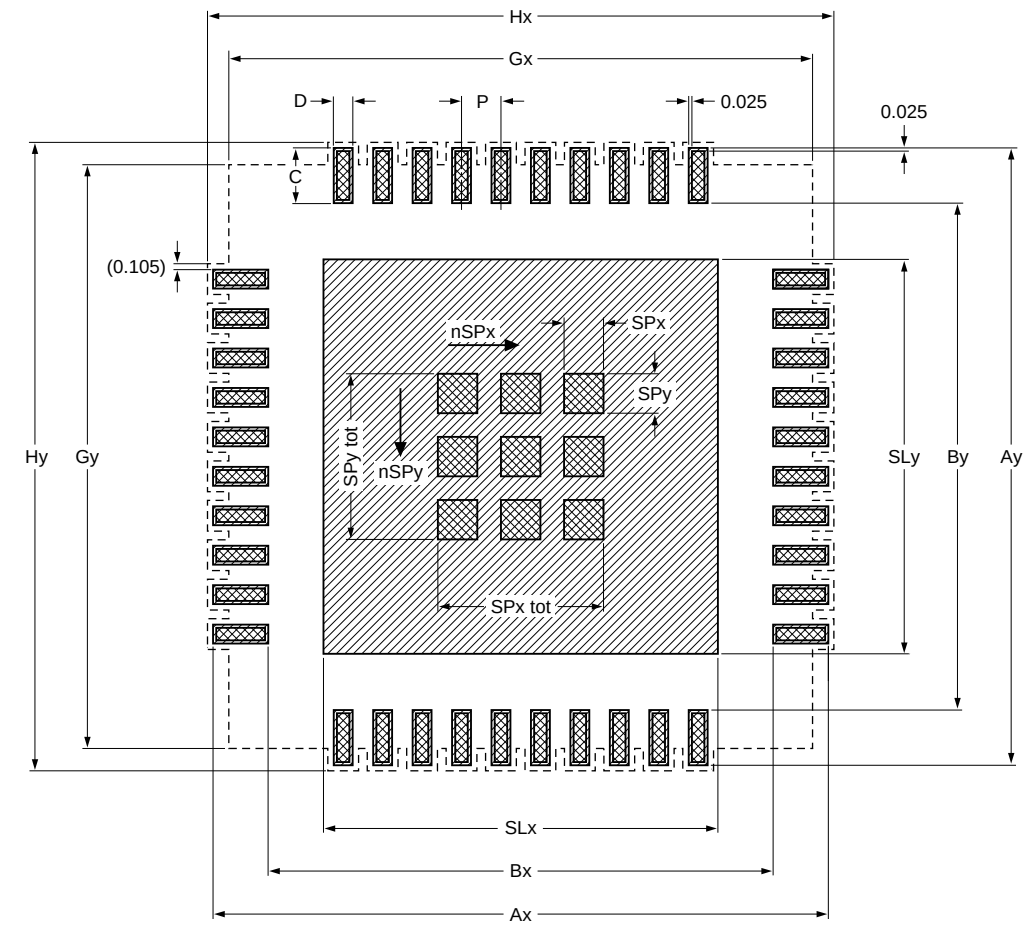
Footprint information for reflow soldering of HVQFN16 package **SOT629-1**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
2	2

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.650	5.000	5.000	2.800	2.800	1.100	0.300	2.000	2.000	1.200	1.200	0.450	0.450	4.300	4.300	5.250	5.250

Issue date ~~07-05-07~~ 09-06-15 *sot629-1_fr*

Fig 28. PCB footprint for SOT629-1 (HVQFN16); reflow soldering

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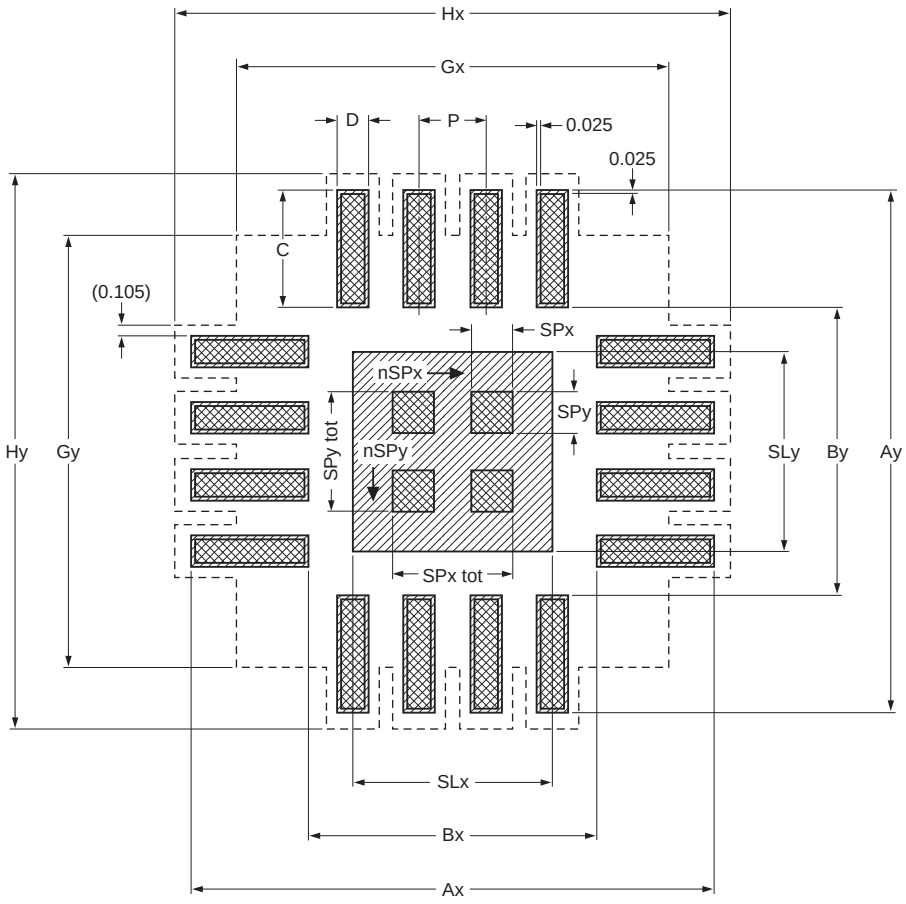
Footprint information for reflow soldering of HVQFN16 package **SOT758-1**



solder land

solder paste deposit

solder land plus solder paste

occupied area

nSPx	nSPy
2	2

Dimensions in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.50	4.00	4.00	2.20	2.20	0.90	0.24	1.50	1.50	0.90	0.90	0.30	0.30	3.30	3.30	4.25	4.25

Issue date ~~12-03-07~~ 12-03-08

sot758-1_fr

Fig 29. PCB footprint for SOT758-1 (HVQFN16); reflow soldering

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15. Abbreviations

Table 14. Abbreviations

Acronym	Description
ACPI	Advanced Configuration and Power Interface
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
FET	Field-Effect Transistor
GPIO	General Purpose Input/Output
HBM	Human Body Model
I^2C-bus	Inter-Integrated Circuit bus
I/O	Input/Output
LED	Light-Emitting Diode
MM	Machine Model
PCB	Printed-Circuit Board
POR	Power-On Reset
SMBus	System Management Bus

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16. Revision history

Table 15. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCA9554_9554A v.10	20171108	Product data sheet	-	PCA9554_9554A v.9
Modifications:	• Table 10 “Static characteristics”: Corrected V_{POR} typ and max limit			
PCA9554_9554A v.9	20130319	Product data sheet	-	PCA9554_9554A v.8
Modifications:	• Removed DIP16 package option (type numbers PCA9554N and PCA9554AN) • Added Section 3.1 “Ordering options” • Deleted (old) Figure 2, “Pin configuration for DIP16” • Figure 10 “PCA9554A device address” modified: label corrected from “programmable” to “hardware selectable” • Figure 16 “Definition of timing” modified: added $0.7 \times V_{DD}$ and $0.3 \times V_{DD}$ reference lines • Deleted (old) Figure 18, “Package outline SOT38-4 (DIP16)” • Deleted (old) Section 14, “Soldering of through-hole mount packages” • Added Section 14 “Soldering: PCB footprints”			
PCA9554_9554A v.8	20110726	Product data sheet	-	PCA9554_9554A v.7
PCA9554_9554A v.7	20061113	Product data sheet	-	PCA9554_9554A v.6
PCA9554_9554A v.6 (9397 750 13289)	20040930	Product data	-	PCA9554_9554A v.5
PCA9554_9554A v.5 (9397 750 10163)	20020726	Product data	853-2243 28672 of 26 July 2002	PCA9554_9554A v.4
PCA9554_9554A v.4 (9397 750 09817)	20020513	Product specification	-	PCA9554_9554A v.3
PCA9554_9554A v.3 (9397 750 08342)	20010507	Product specification	-	PCA9554_9554A v.2
PCA9554_9554A v.2 (9397 750 08209)	20010319	Product specification	-	PCA9554_9554A v.1
PCA9554_9554A v.1 (9397 750 08159)	20010319	Product specification	-	-

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Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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